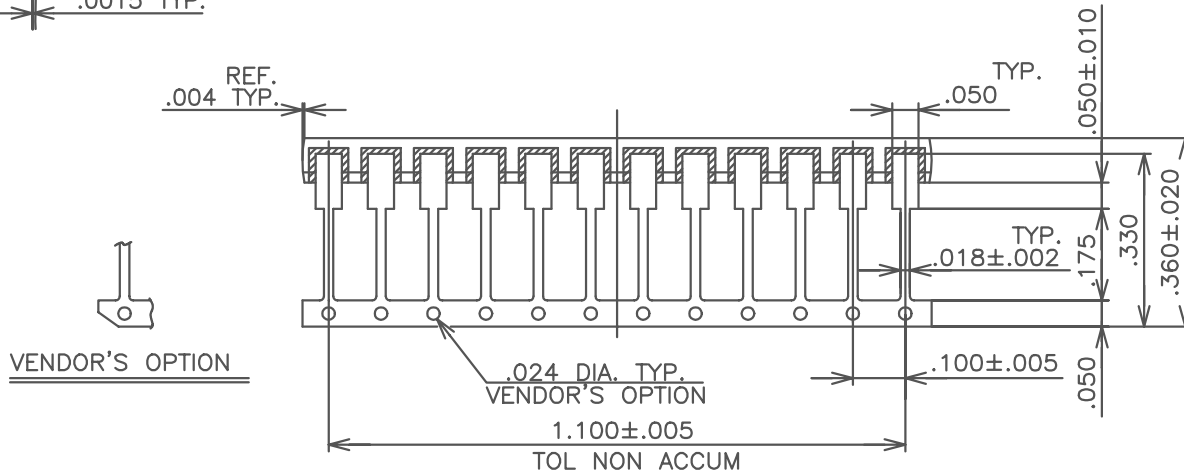
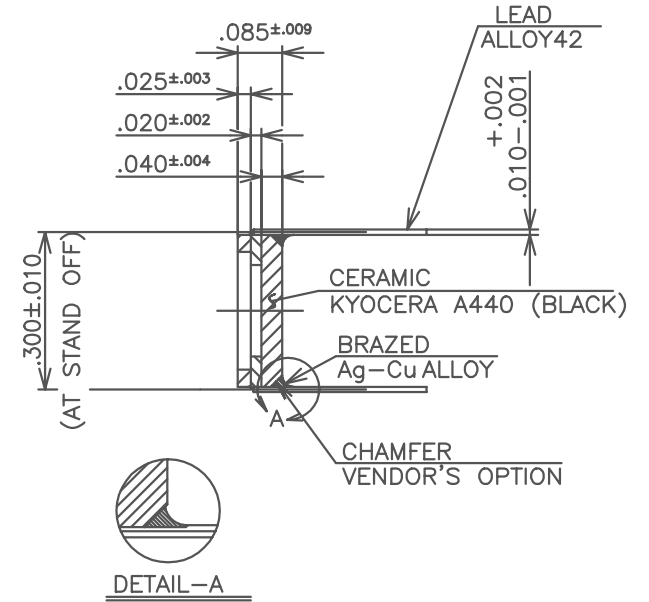
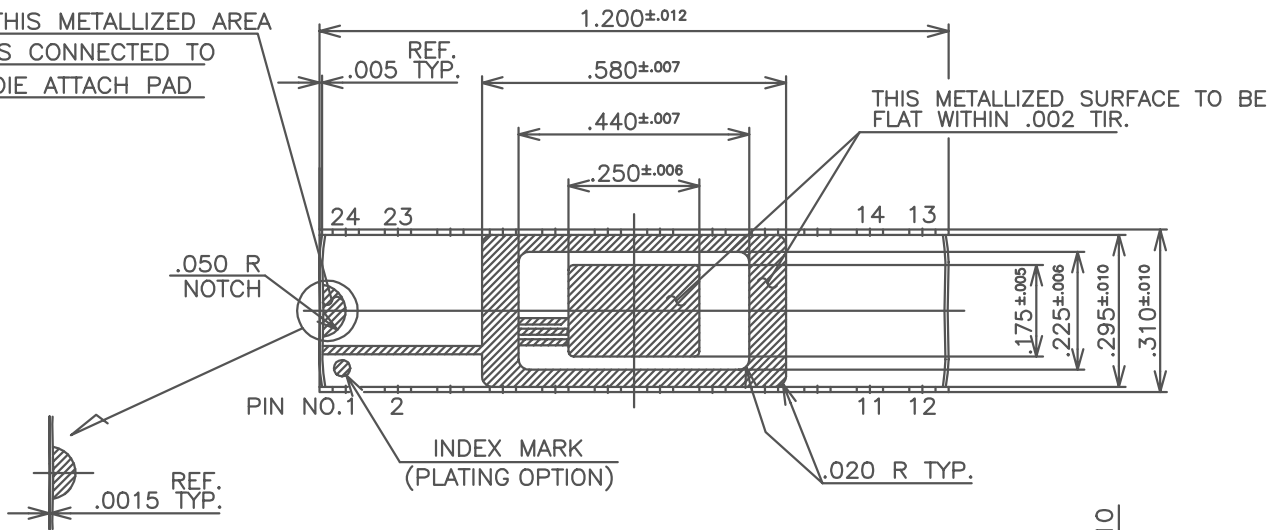


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD



NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.3 Ω MAX.
6. DIE ATTACH PAD TO BE ELECTRICALLY CONNECTED TO BONDING PAD "GND".

SB024M831-1 S=0 D=0

MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED	DATE	NAME		TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
							24 LEAD SIDE BRAZED PACKAGE		UNLESS OTHERWISE SPECIFIED	M.S	S.T/T.A	M.K	AUG.06.'91
△	REDRAWN : (CAD DATA)	AUG.06.'91	M.S	S.T/TA	M.K		SCALE	4 / 1	±.005				
△	ADDED : .018 TYP. MIN.	JUN.06.'83	M.M	K.M			MATERIAL	AS INDICATED	THIRD ANGLE PROJECTION				
△	ADDED : .005REF., .0015REF., .004REF.	JAN.28.'83	N.I	K.M									
	CHANGED	DATE	DRAWN	CHECKED	APPROVED								
									KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-82831-C		SHEET 1 / 2

